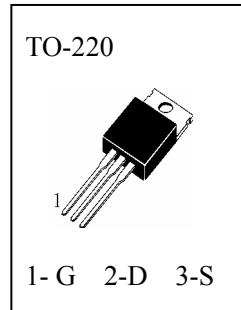




N-Channel Enhancement Mode Field Effect Transistor

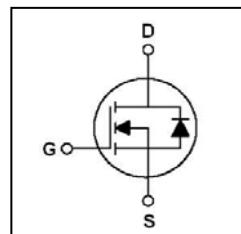
■ General Description

These power MOSFETs is designed for high voltage, high speed power switching applications such as switching regulators, converters, solenoid and relay drivers. And DC-DC&DC-AC Converters for Telecom, Industrial and Consumer Environment



■ Features

- 18A, 200V, $R_{DS(on)} < 0.18\Omega$ @ $V_{GS} = 10\text{ V}$
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability
- Equivalent Type: IRF640



■ Maximum Ratings (Ta=25°C unless otherwise specified)

| | | |
|---|-------|------------|
| T_{stg} —— Storage Temperature | ----- | -55~150 °C |
| T_j —— Operating Junction Temperature | ----- | 150 °C |
| V_{DSS} —— Drain-Source Voltage | ----- | 200V |
| V_{DGR} —— Drain-Gate Voltage ($R_{GS}=20\text{k}\Omega$) | ----- | 200V |
| V_{GSS} —— Gate-Source Voltage | ----- | ±20V |
| I_D —— Drain Current (Continuous) | ----- | 18A |
| P_D —— Maximum Power Dissipation | ----- | 125W |
| I_{AR} —— Avalanche Current, Repetitive or Not-Repetitive (pulse width limited by T_j max, $d < 1\%$) | ----- | 18A |
| E_{AS} —— Single Pulse Avalanche Energy (starting $T_j = 25\text{ °C}$, $I_D = I_{AR}$, $V_{DD} = 50\text{ V}$) | ----- | 320mJ |
| E_{AR} —— Repetitive Avalanche Energy(pulse width limited by T_j max, $d < 1\%$) | ----- | 13.4mJ |

■ Thermal Characteristics

| Symbol | Items | TO-220 | Unit |
|----------------|-------------------------------------|----------|------|
| $R_{thj-case}$ | Thermal Resistance Junction-case | Max 1.0 | °C/W |
| $R_{thj-amb}$ | Thermal Resistance Junction-ambient | Max 62.5 | °C/W |
| $R_{th c-s}$ | Thermal Resistance Case-sink | Typ 0.5 | °C/W |



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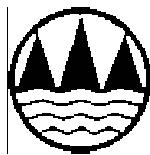
HFP640

■ Electrical Characteristics (Ta=25°C unless otherwise specified)

| Symbol | Items | Min. | Typ. | Max. | Unit | Conditions |
|---|---|------|------|------|---|---|
| Off Characteristics | | | | | | |
| BV _{DSS} | Drain-Source Breakdown Voltage | 200 | | | V | I _D =250μA , V _{GS} =0V |
| I _{DSS} | Zero Gate Voltage Drain Current | | 25 | μA | V _{DS} =200V, V _{GS} =0V | |
| | | | 250 | μA | V _{DS} =160V, V _{GS} =0V,Tj=125°C | |
| I _{GSS} | Gate – Body Leakage | | ±100 | nA | V _{GS} = ±20V , V _{DS} =0V | |
| On Characteristics | | | | | | |
| V _{GS(th)} | Gate Threshold Voltage | 2.0 | | 4.0 | V | V _{DS} = V _{GS} , I _D =250μA |
| R _{DS(on)} | Static Drain-Source On-Resistance | | | 0.18 | Ω | V _{GS} =10V, I _D =9A |
| g _{FS} | Forward Transconductance | 4.3 | | | S | V _{DS} =40V, I _D =9A (Note 1) |
| Dynamic Characteristics and Switching Characteristics | | | | | | |
| C _{iss} | Input Capacitance | | | 1700 | pF | V _{DS} = 25 V, V _{GS} = 0 V, f = 1.0 MHz |
| C _{oss} | Output Capacitance | | | 230 | pF | |
| C _{rss} | Reverse Transfer Capacitance | | | 60 | pF | |
| t _{d(on)} | Turn - On Delay Time | | | 50 | nS | V _{DD} = 100 V, I _D = 18Apk R _G = 25 Ω (Note 1,2) |
| tr | Rise Time | | | 300 | nS | |
| t _{d(off)} | Turn - Off Delay Time | | | 300 | nS | |
| t _f | Fall Time | | | 230 | nS | |
| Q _g | Total Gate Charge | | 45 | 58 | nC | V _{DS} =0.8V _{DSS} , ID=18A, V _{GS} = 10 V (Note 1,2) |
| Q _{gs} | Gate–Source Charge | | 6.5 | | nC | |
| Q _{gd} | Gate–Drain Charge | | 22 | | nC | |
| Drain-Source Diode Characteristics and Maximum Ratings | | | | | | |
| I _S | Continuous Source–Drain Diode Forward Current | | | 18 | A | |
| I _{SM} | Pulsed Drain-Source Diode Forward Current | | | 72 | A | |
| V _{SD} | Source–Drain Diode Forward On–Voltage | | | 1.5 | V | I _S =18A,V _{GS} =0 |

Notes:

1. Pulse Test: Pulse width≤300 μ S, Duty cycle≤2%
2. Essentially independent of operating temperature



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HFP640

■ Typical Characteristics

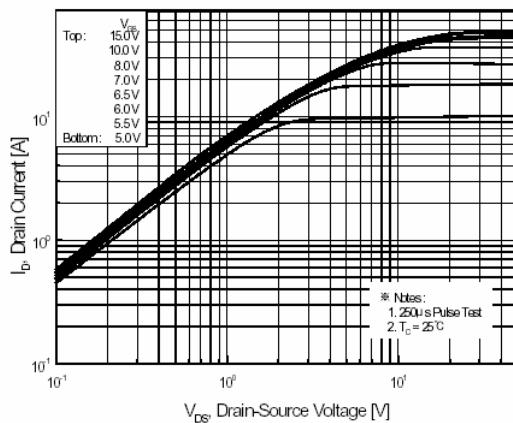


Figure 1. On-Region Characteristics

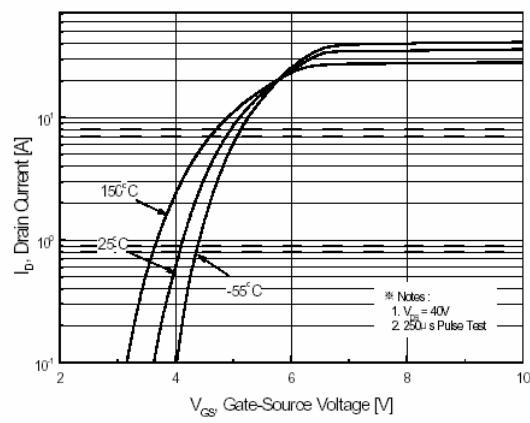


Figure 2. Transfer Characteristics

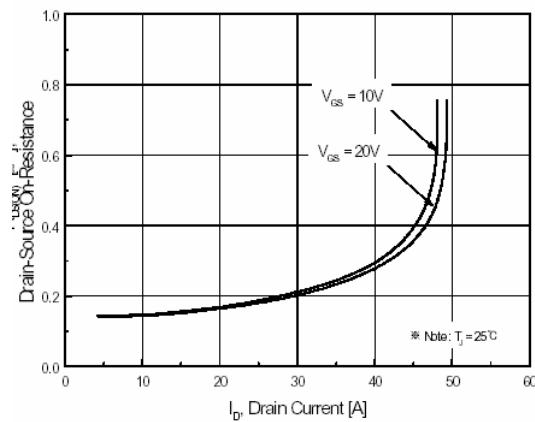


Figure 3. On-Resistance Variation vs
Drain Current and Gate Voltage

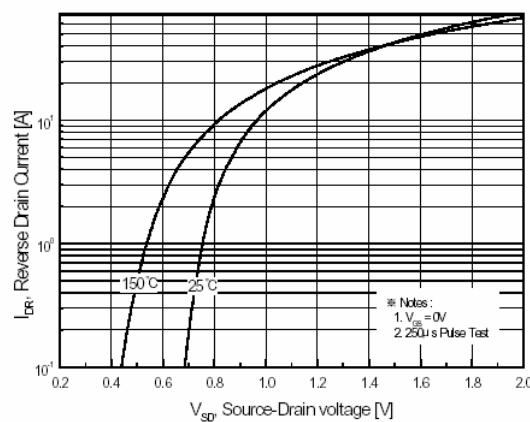


Figure 4. Body Diode Forward Voltage
Variation with Source Current
and Temperature

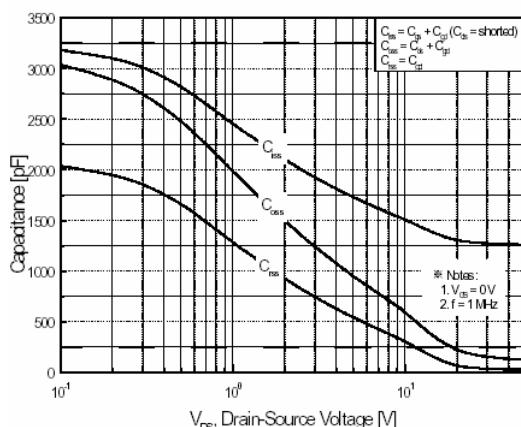


Figure 5. Capacitance Characteristics

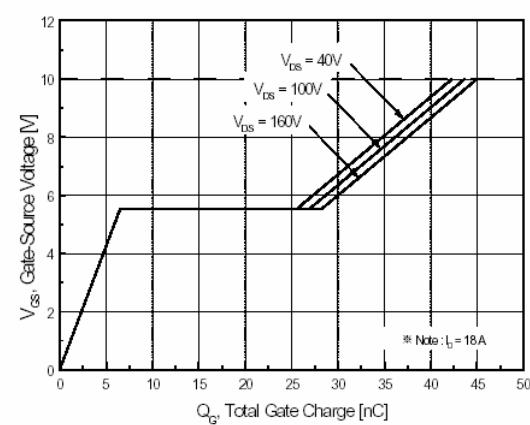


Figure 6. Gate Charge Characteristics



■ Typical Characteristics

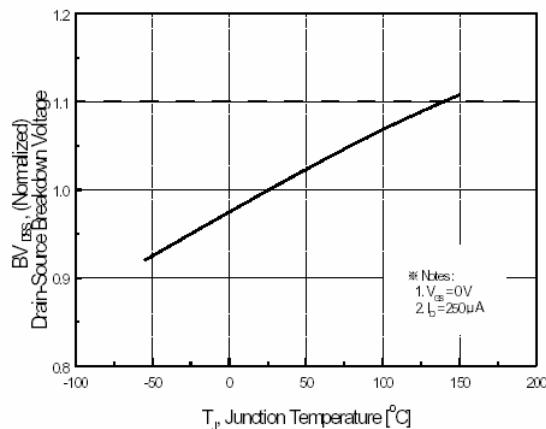


Figure 7. Breakdown Voltage Variation vs Temperature

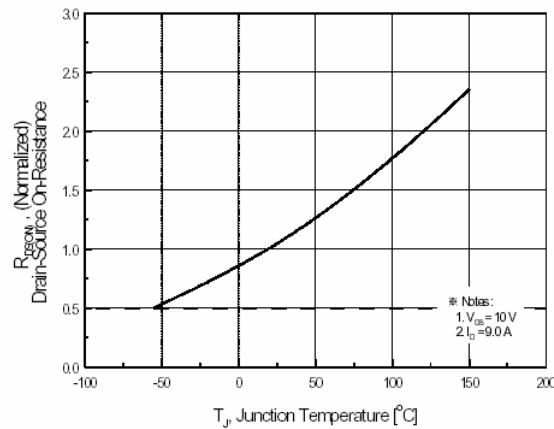


Figure 8. On-Resistance Variation vs Temperature

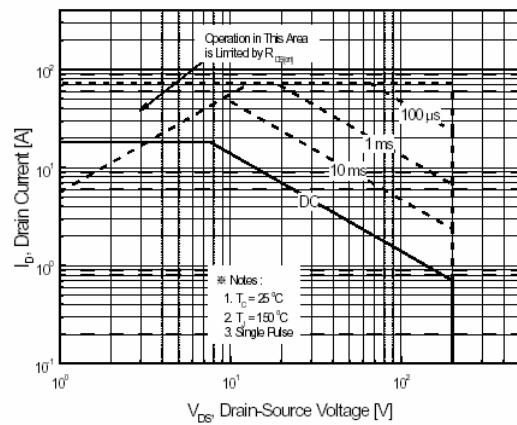


Figure 9. Maximum Safe operating Area

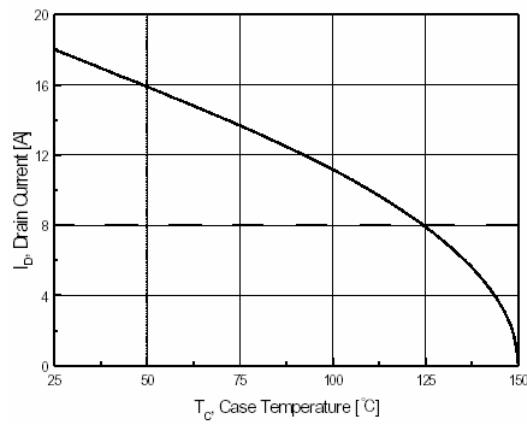


Figure 10. Maximum Drain Current vs Case Temperature

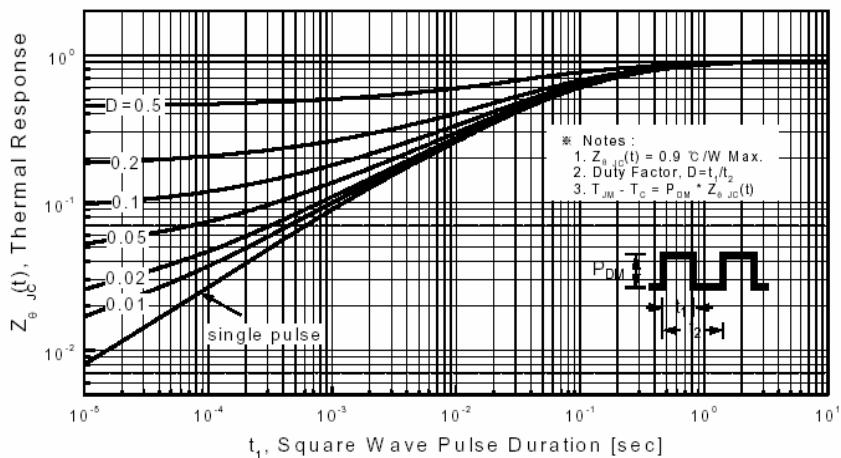
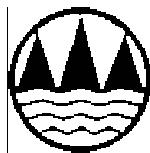


Figure 11. Transient Thermal Response Curve

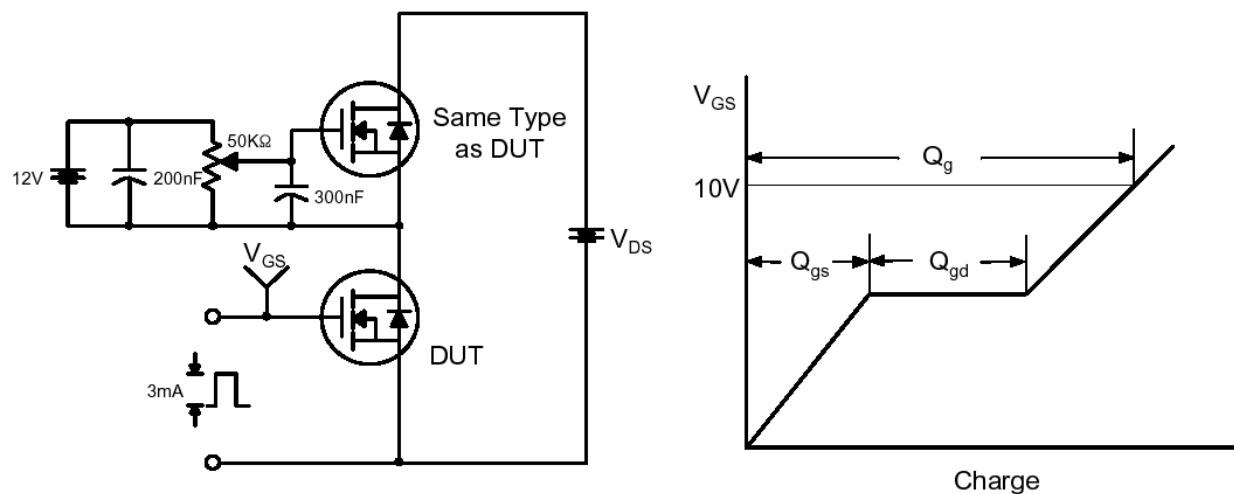


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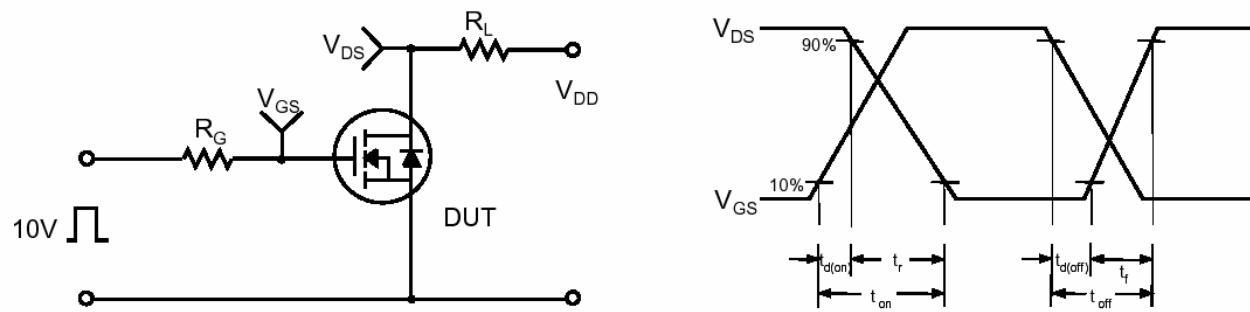
HFP640

■ Typical Characteristics

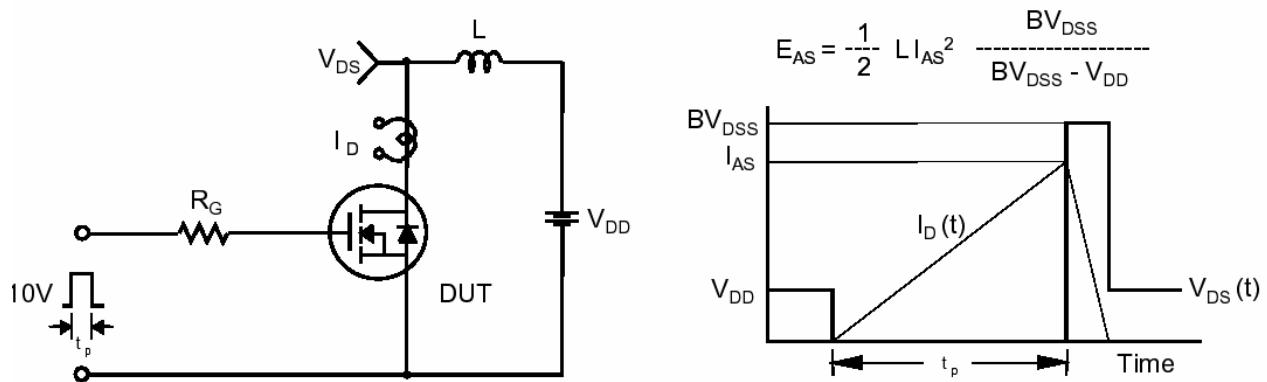
Gate Charge Test Circuit & Waveform

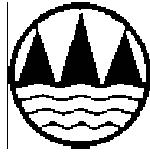


Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms





■ Typical Characteristics

Peak Diode Recovery dv/dt Test Circuit & Waveforms

